

7WBD3125

2-Bit Translating Bus Switch

The 7WBD3125 is an advanced high-speed low-power 2-bit translating bus switch in ultra-small footprints.

Features


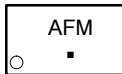

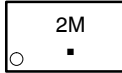

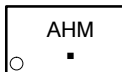

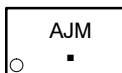

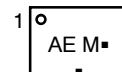



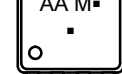
- High Speed: $t_{PD} = 0.25$ ns (Max) @ $V_{CC} = 4.5$ V
- $3\ \Omega$ Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Zero Bounce
- TTL-Compatible Control Inputs
- Ultra-Small Pb-Free Packages
- These are Pb-Free Devices



ON Semiconductor®

<http://onsemi.com>

MARKING DIAGRAMS

| | | |
|--|---|---|
|  | UDFN8 MU SUFFIX CASE 517AJ |  |
|  | ULLGA8 1.45 x 1.0 CASE 613AA |  |
|  | ULLGA8 1.6 x 1.0 CASE 613AB |  |
|  | ULLGA8 1.95 x 1.0 CASE 613AC |  |
|  | UQFN8 MU SUFFIX CASE 523AN |  |
|  | US8 US SUFFIX CASE 493 |  |
|  | Micro8™ DM SUFFIX CASE 846A |  |

A = Assembly Location
 Y = Year
 W = Work Week
 M = Date Code
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

This document contains information on some products that are still under development. ON Semiconductor reserves the right to change or discontinue these products without notice.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

7WBD3125

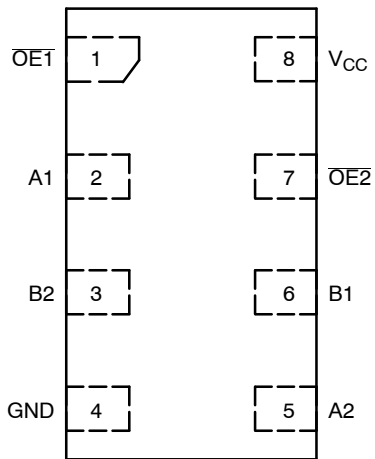


Figure 1. ULLGA8/UDFN8
(Top Thru-View)

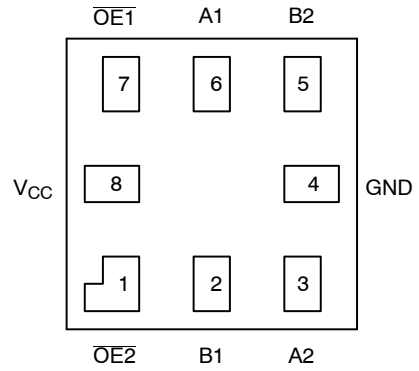


Figure 2. UQFN8
(Top Thru-View)

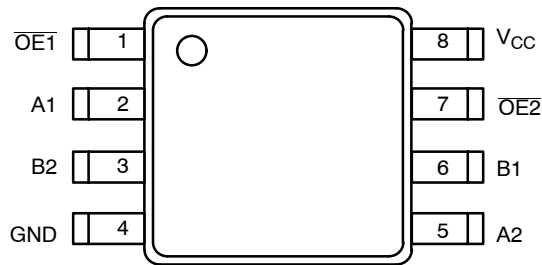


Figure 3. US8/Micro8
(Top View)

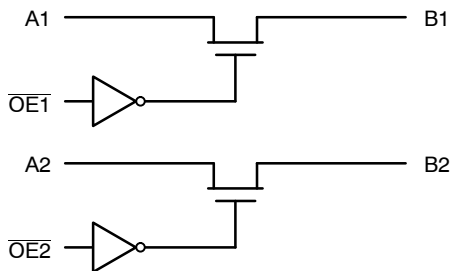


Figure 4. Logic Diagram

FUNCTION TABLE

| Input $\overline{OE}n$ | Function |
|------------------------|------------|
| L | $Bn = An$ |
| H | Disconnect |

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MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit | |
|---------------|--|-------------------------------|-------------|---------------|
| V_{CC} | DC Supply Voltage | -0.5 to +7.0 | V | |
| V_{IN} | Control Pin Input Voltage | -0.5 to +7.0 | V | |
| $V_{I/O}$ | Switch Input / Output Voltage | -0.5 to +7.0 | V | |
| I_{IK} | Control Pin DC Input Diode Current $V_{IN} < GND$ | -50 | mA | |
| I_{OK} | Switch I/O Port DC Diode Current $V_{I/O} < GND$ | -50 | mA | |
| I_O | ON-State Switch Current | ± 128 | mA | |
| | Continuous Current Through V_{CC} or GND | ± 150 | mA | |
| I_{CC} | DC Supply Current Per Supply Pin | ± 150 | mA | |
| I_{GND} | DC Ground Current per Ground Pin | ± 150 | mA | |
| T_{STG} | Storage Temperature Range | -65 to +150 | $^{\circ}C$ | |
| T_L | Lead Temperature, 1 mm from Case for 10 Seconds | 260 | $^{\circ}C$ | |
| T_J | Junction Temperature Under Bias | 150 | $^{\circ}C$ | |
| θ_{JA} | Thermal Resistance | US8 (Note 1) | 251 | $^{\circ}C/W$ |
| | | UDFN8 | 111 | |
| | | UQFN8 | 208 | |
| | | ULLGA8 | 455 | |
| | | Micro8 | 392 | |
| P_D | Power Dissipation in Still Air at 85 $^{\circ}C$ | US8 | 498 | mW |
| | | UDFN8 | 1127 | |
| | | UQFN8 | 601 | |
| | | ULLGA8 | 274 | |
| | | Micro8 | 319 | |
| MSL | Moisture Sensitivity | Level 1 | | |
| F_R | Flammability Rating Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | | |
| V_{ESD} | ESD Withstand Voltage | Human Body Mode (Note 2) | > 2000 | V |
| | | Machine Model (Note 3) | > 200 | |
| | | Charged Device Model (Note 4) | N/A | |
| $I_{LATCHUP}$ | Latchup Performance Above V_{CC} and Below GND at 125 $^{\circ}C$ (Note 5) | ± 200 | mA | |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA / JESD22-A114-A.
3. Tested to EIA / JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit | |
|-----------------------|------------------------------------|---------------|------|-------------|------|
| V_{CC} | Positive DC Supply Voltage | 4.0 | 5.5 | V | |
| V_{IN} | Control Pin Input Voltage | 0 | 5.5 | V | |
| $V_{I/O}$ | Switch Input / Output Voltage | 0 | 5.5 | V | |
| T_A | Operating Free-Air Temperature | -55 | +125 | $^{\circ}C$ | |
| $\Delta t / \Delta V$ | Input Transition Rise or Fall Rate | Control Input | 0 | 5 | nS/V |
| | | Switch I/O | 0 | DC | |

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DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = 25°C | | | T _A = -55°C to +125°C | | Unit |
|------------------|---|---|------------------------|-----------------------|--------|--------------|-------------------------------------|--------------|----------|
| | | | | Min | Typ | Max | Min | Max | |
| V _{IK} | Clamp Diode Voltage | I _{I/O} = -18 mA | 4.5 | | | -1.2 | | -1.2 | V |
| V _{IH} | High-Level Input Voltage (Control) | | 4.0 to 5.5 | 2.0 | | | 2.0 | | V |
| V _{IL} | Low-Level Input Voltage (Control) | | 4.0 to 5.5 | | | 0.8 | | 0.8 | V |
| V _{OH} | Output Voltage High | See Figure 5 | | | | | | | |
| I _{IN} | Input Leakage Current | 0 ≤ V _{IN} ≤ 5.5 V | 5.5 | | | ±0.1 | | ±1.0 | μA |
| I _{OFF} | Power Off Leakage Current | V _{I/O} = 0 to 5.5 V | 0 | | | ±0.1 | | ±1.0 | μA |
| I _{CC} | Quiescent Supply Current | I _O = 0, V _{IN} = V _{CC} or 0 V OE1 = OE2 = GND OE1 = OE2 = V _{CC} | 5.5 | | | ±1.0 ±0.1 | | ±1.0 ±1.0 | mA μA |
| ΔI _{CC} | Increase in Supply Current (Control Pin) | One input at 3.4 V; Other inputs at V _{CC} or GND | 5.5 | | | | | 2.5 | mA |
| R _{ON} | Switch ON Resistance | V _{I/O} = 0, I _{I/O} = 64 mA I _{I/O} = 30 mA | 4.5 | | 3 3 | 7 7 | | 7 7 | Ω |
| | | V _{I/O} = 2.4, I _{I/O} = 15 mA | | | 15 | 50 | | 50 | |
| | | V _{I/O} = 2.4, I _{I/O} = 15 mA | 4.0 | | 50 | 70 | | 70 | |

AC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Condition | V _{CC} (V) | T _A = 25 °C | | | T _A = -55°C to +125°C | | Unit |
|----------------------|-------------------------------|----------------------------|------------------------|------------------------|-----|------|-------------------------------------|------|------|
| | | | | Min | Typ | Max | Min | Max | |
| t _{PD} | Propagation Delay, Bus to Bus | See Figure 6 | 4.0 to 5.5 | | | 0.25 | | 0.25 | ns |
| t _{EN} | Output Enable Time | See Figure 6 | 4.5 to 5.5 | 0.8 | 2.5 | 4.2 | 0.8 | 4.2 | ns |
| | | | 4.0 | 0.8 | 3.0 | 4.6 | 0.8 | 4.6 | |
| t _{DIS} | Output Disable Time | | 4.5 to 5.5 | 0.8 | 3.0 | 4.8 | 0.8 | 4.8 | ns |
| | | | 4.0 | 0.8 | 2.9 | 4.4 | 0.8 | 4.4 | |
| C _{IN} | Control Input Capacitance | V _{IN} = 5 or 0 V | 5.0 | | 2.5 | | | | pF |
| C _{IO(ON)} | Switch On Capacitance | Switch ON | 5.0 | | 10 | | | | pF |
| C _{IO(OFF)} | Switch Off Capacitance | Switch OFF | 5.0 | | 5 | | | | pF |

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TYPICAL DC CHARACTERISTICS

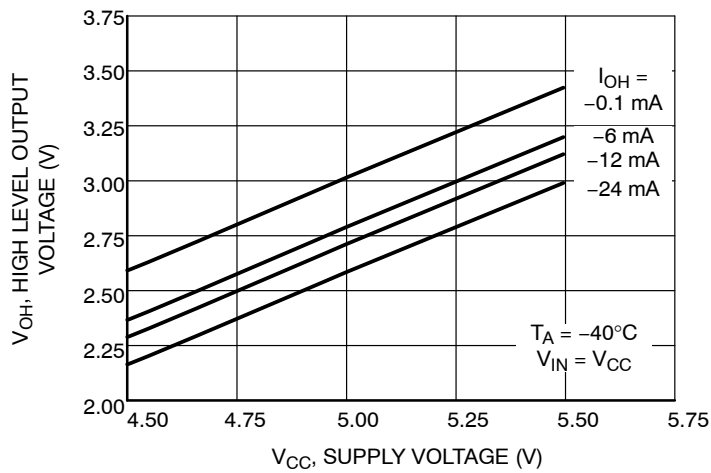
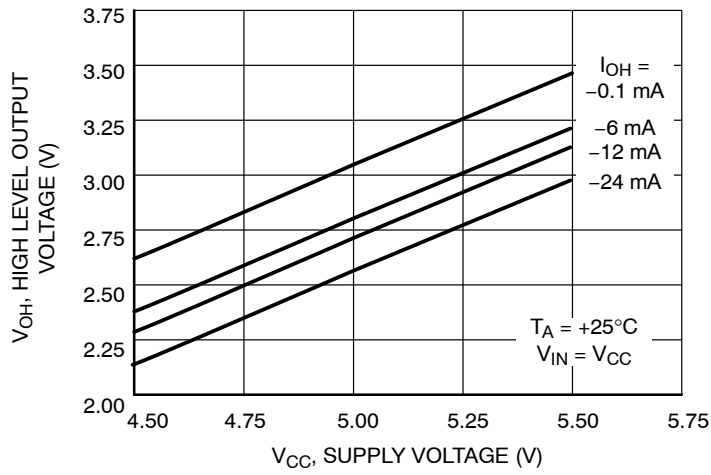
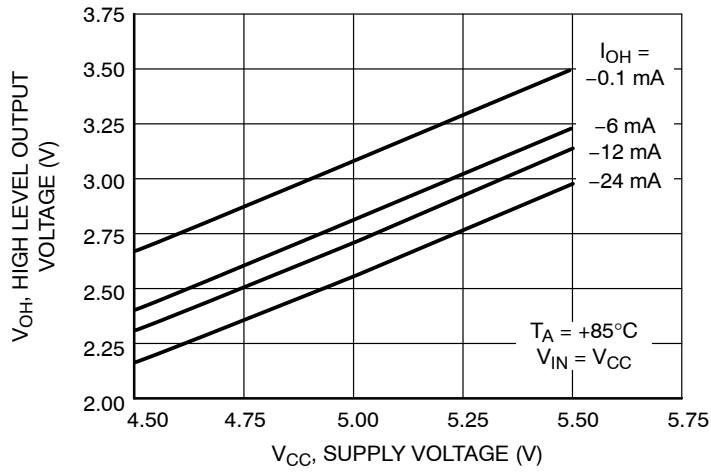
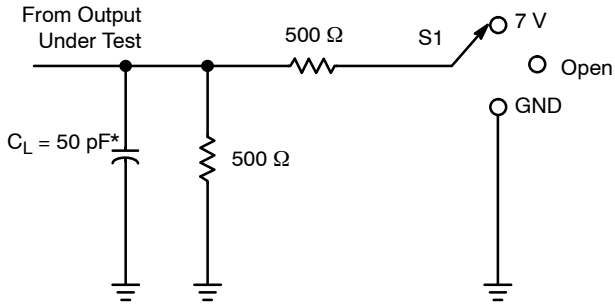


Figure 5. Output Voltage High vs Supply Voltage

7WBD3125

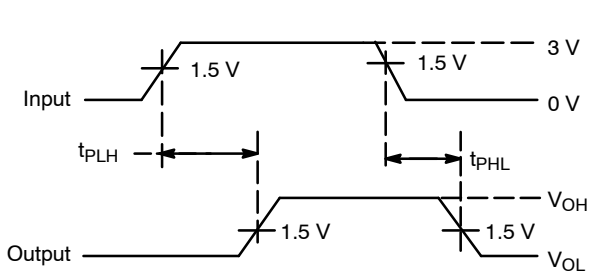
AC LOADING AND WAVEFORMS

Parameter Measurement Information

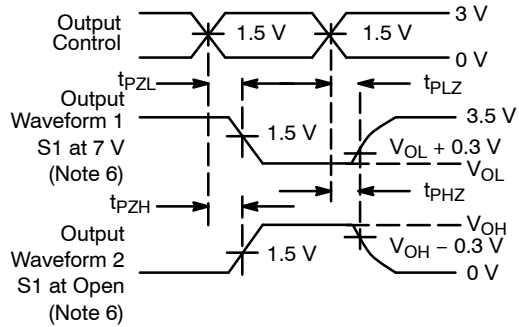


* C_L includes probes and jig capacitance.

| Test | S1 |
|-------------------|------|
| t_{PD} | Open |
| t_{PLZ}/t_{PZL} | 7 V |
| t_{PHZ}/t_{PZH} | Open |



**Voltage Waveforms
Propagation Delay Times**



**Voltage Waveforms
Enable and Disable Times**

6. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control
7. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
8. The outputs are measured one at a time, with one transition per measurement.
9. t_{PLZ} and t_{PHZ} are the same as t_{DIS} .
10. t_{PZL} and t_{PZH} are the same as t_{EN} .
11. t_{PHL} and t_{PLH} are the same as t_{PD} .

Figure 6. t_{PD} , t_{EN} , t_{DIS} Loading and Waveforms

ORDERING INFORMATION

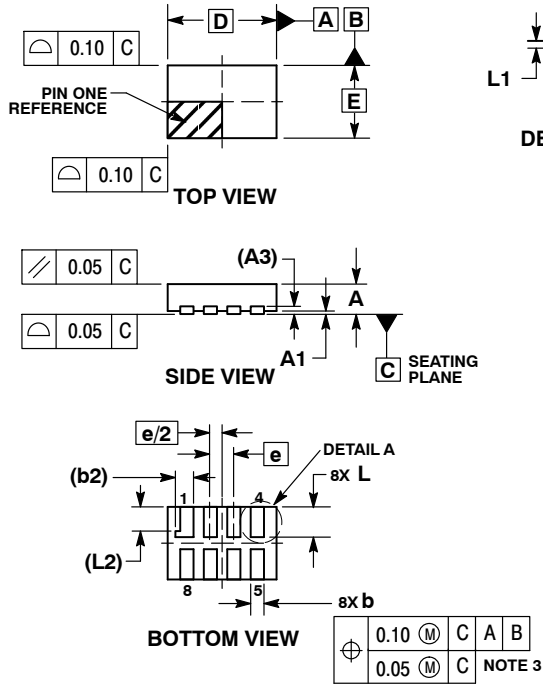
| Device | Package | Shipping† |
|-----------------|-------------------------------------|--|
| 7WBD3125USG | US8 (Pb-Free) | 3000 / Tape & Reel |
| 7WBD3125MUTAG | UDFN8 (Pb-Free) | 3000 / Tape & Reel |
| 7WBD3125AMUTCG | UQFN8 (Pb-Free) | 3000 / Tape & Reel |
| 7WBD3125AMX1TCG | ULLGA8 – 0.5 mm Pitch (Pb-Free) | 3000 / Tape & Reel |
| 7WBD3125BMX1TCG | ULLGA8 – 0.4 mm Pitch (Pb-Free) | 3000 / Tape & Reel |
| 7WBD3125CMX1TCG | ULLGA8 – 0.35 mm Pitch (Pb-Free) | 3000 / Tape & Reel |
| 7WBD3125DMR2G | Micro8 (Pb-Free) | 4000 / Tape & Reel (In Development) |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

UDFN8 1.8 x 1.2, 0.4P
CASE 517AJ-01
ISSUE O

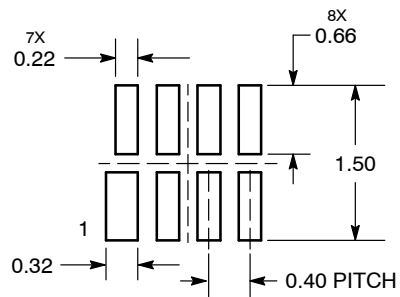


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

| MILLIMETERS | | |
|-------------|-------|------|
| DIM | MIN | MAX |
| A | 0.45 | 0.55 |
| A1 | 0.00 | 0.05 |
| A3 | 0.127 | REF |
| b | 0.15 | 0.25 |
| b2 | 0.30 | REF |
| D | 1.80 | BSC |
| E | 1.20 | BSC |
| e | 0.40 | BSC |
| L | 0.45 | 0.55 |
| L1 | 0.00 | 0.03 |
| L2 | 0.40 | REF |

**MOUNTING FOOTPRINT*
SOLDERMASK DEFINED**



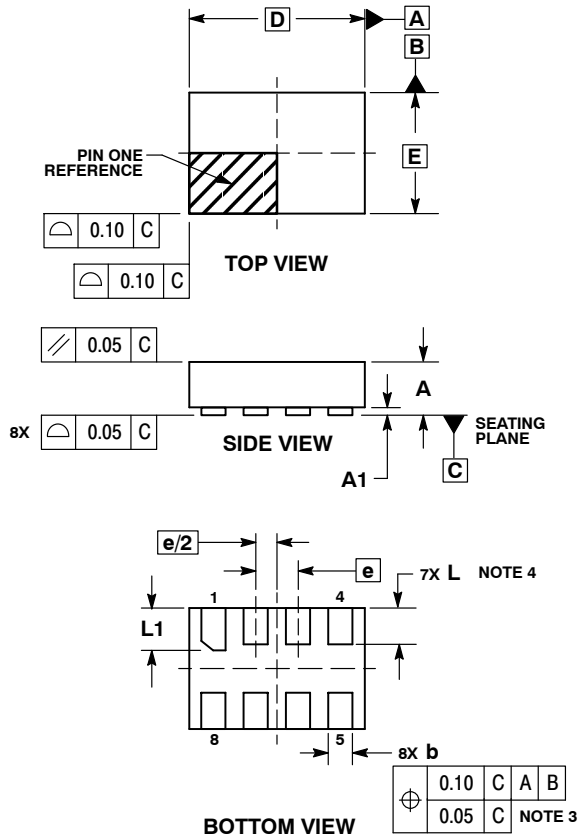
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

7WBD3125

PACKAGE DIMENSIONS

ULLGA8 1.45x1.0, 0.35P
CASE 613AA-01
ISSUE A

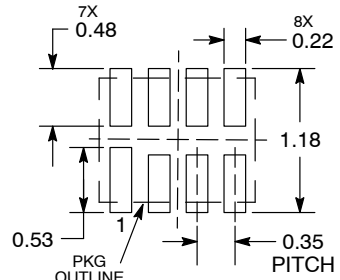


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | --- | 0.40 |
| A1 | 0.00 | 0.05 |
| b | 0.15 | 0.25 |
| D | 1.45 BSC | |
| E | 1.00 BSC | |
| e | 0.35 BSC | |
| L | 0.25 | 0.35 |
| L1 | 0.30 | 0.40 |

**MOUNTING FOOTPRINT
SOLDERMASK DEFINED***



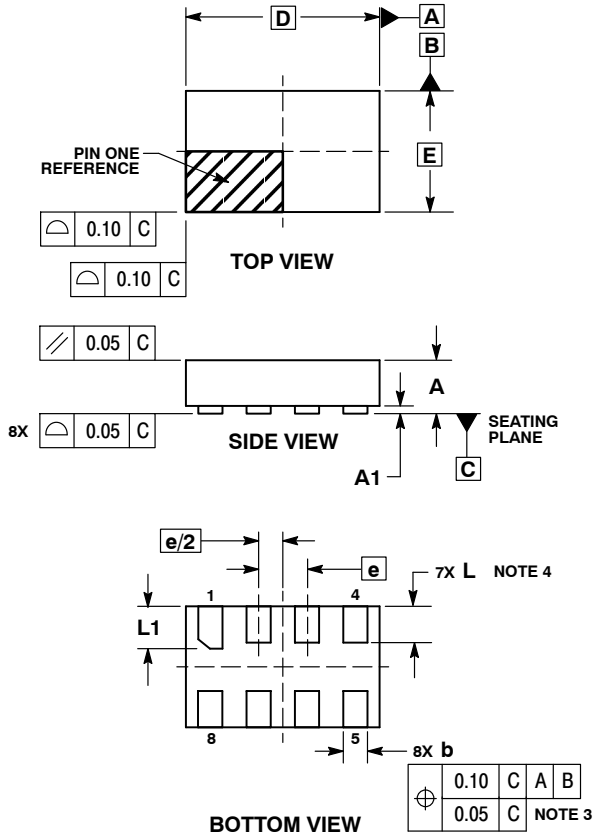
DIMENSIONS: MILLIMETERS

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7WBD3125

PACKAGE DIMENSIONS

ULLGA8 1.6x1.0, 0.4P
CASE 613AB-01
ISSUE A

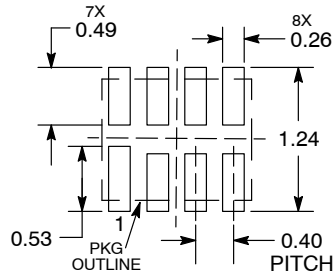


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2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

| MILLIMETERS | | |
|-------------|----------|------|
| DIM | MIN | MAX |
| A | --- | 0.40 |
| A1 | 0.00 | 0.05 |
| b | 0.15 | 0.25 |
| D | 1.60 BSC | |
| E | 1.00 BSC | |
| e | 0.40 BSC | |
| L | 0.25 | 0.35 |
| L1 | 0.30 | 0.40 |

**MOUNTING FOOTPRINT
SOLDERMASK DEFINED***



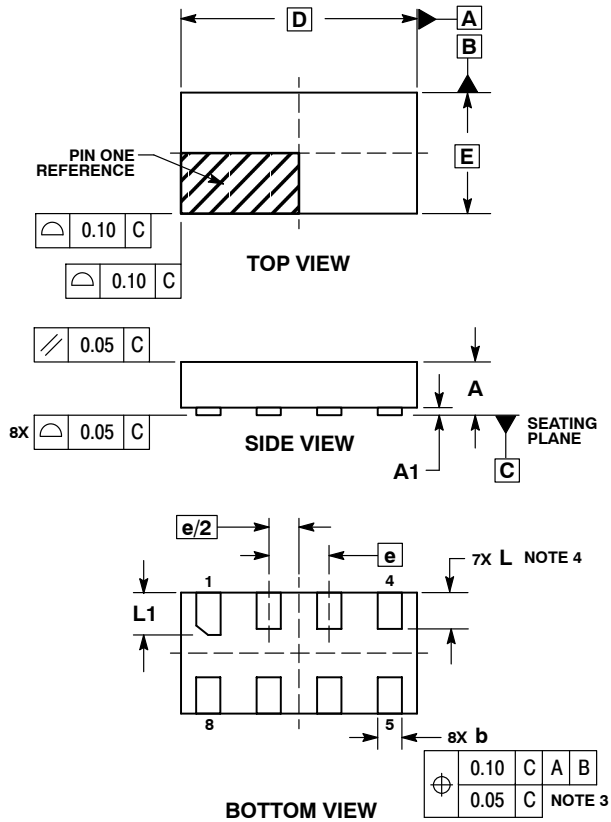
DIMENSIONS: MILLIMETERS

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7WBD3125

PACKAGE DIMENSIONS

ULLGA8 1.95x1.0, 0.5P
CASE 613AC-01
ISSUE A

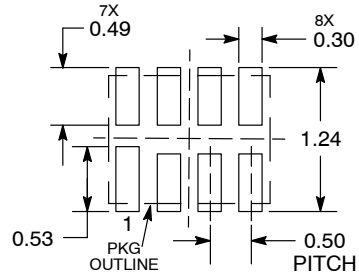


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4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

| MILLIMETERS | | |
|-------------|----------|------|
| DIM | MIN | MAX |
| A | --- | 0.40 |
| A1 | 0.00 | 0.05 |
| b | 0.15 | 0.25 |
| D | 1.95 BSC | |
| E | 1.00 BSC | |
| e | 0.50 BSC | |
| L | 0.25 | 0.35 |
| L1 | 0.30 | 0.40 |

**MOUNTING FOOTPRINT
SOLDERMASK DEFINED***



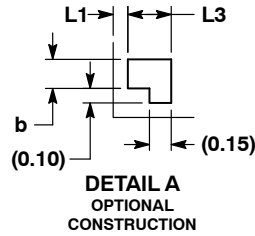
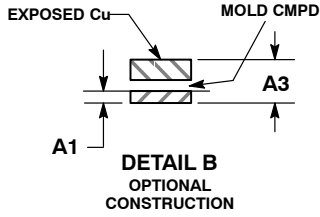
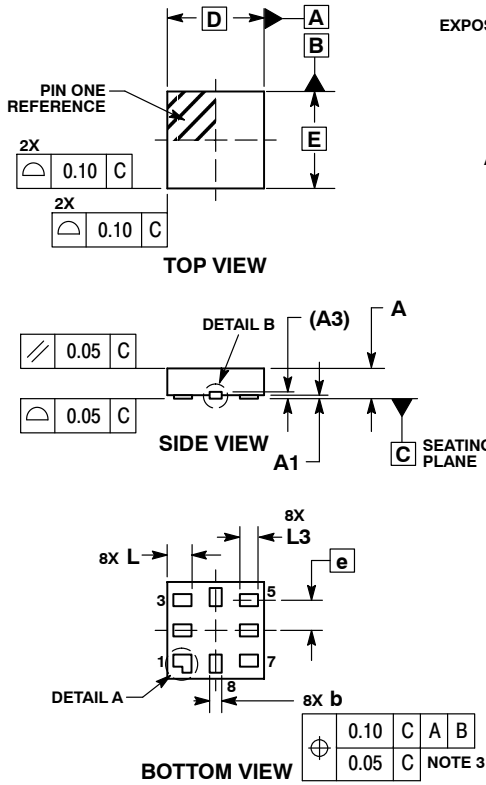
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

7WBD3125

PACKAGE DIMENSIONS

UQFN8, 1.6x1.6, 0.5P
CASE 523AN-01
ISSUE O

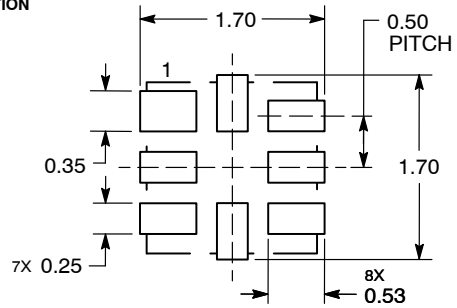


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

| MILLIMETERS | | |
|-------------|------|------|
| DIM | MIN | MAX |
| A | 0.45 | 0.60 |
| A1 | 0.00 | 0.05 |
| A3 | 0.13 | REF |
| b | 0.15 | 0.25 |
| D | 1.60 | BSC |
| E | 1.60 | BSC |
| e | 0.50 | BSC |
| L | 0.35 | 0.45 |
| L1 | --- | 0.15 |
| L3 | 0.25 | 0.35 |

SOLDERING FOOTPRINT*



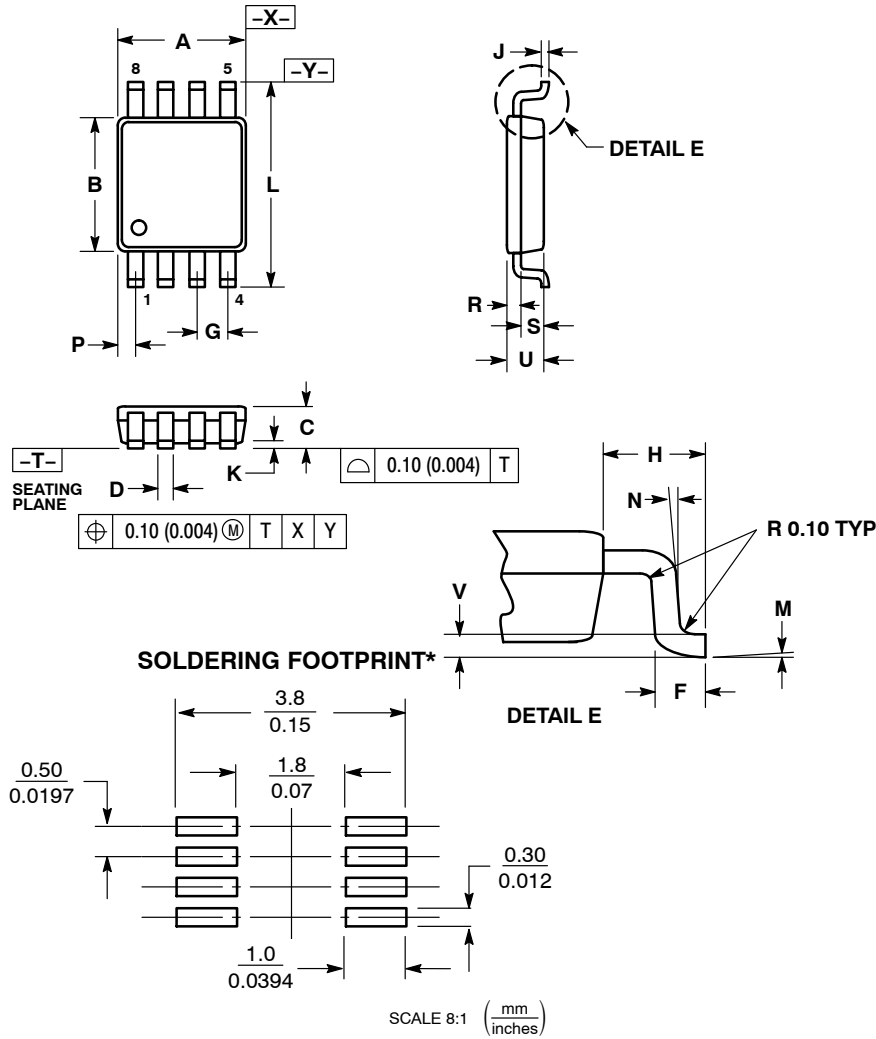
DIMENSIONS: MILLIMETERS

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7WBD3125

PACKAGE DIMENSIONS

US8
CASE 493-02
ISSUE B



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055") PER SIDE.
4. DIMENSION "B" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.140 (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM. (300-800 μ).
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508 (0.0020").

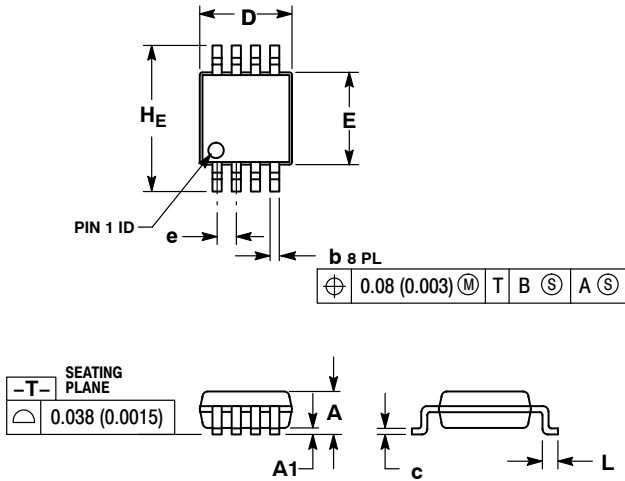
| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.90 | 2.10 | 0.075 | 0.083 |
| B | 2.20 | 2.40 | 0.087 | 0.094 |
| C | 0.60 | 0.90 | 0.024 | 0.035 |
| D | 0.17 | 0.25 | 0.007 | 0.010 |
| F | 0.20 | 0.35 | 0.008 | 0.014 |
| G | 0.50 BSC | | 0.020 BSC | |
| H | 0.40 REF | | 0.016 REF | |
| J | 0.10 | 0.18 | 0.004 | 0.007 |
| K | 0.00 | 0.10 | 0.000 | 0.004 |
| L | 3.00 | 3.20 | 0.118 | 0.126 |
| M | 0° | 6° | 0° | 6° |
| N | 5° | 10° | 5° | 10° |
| P | 0.23 | 0.34 | 0.010 | 0.013 |
| R | 0.23 | 0.33 | 0.009 | 0.013 |
| S | 0.37 | 0.47 | 0.015 | 0.019 |
| U | 0.60 | 0.80 | 0.024 | 0.031 |
| V | 0.12 BSC | | 0.005 BSC | |

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

7WBD3125

PACKAGE DIMENSIONS

Micro8™
CASE 846A-02
ISSUE H

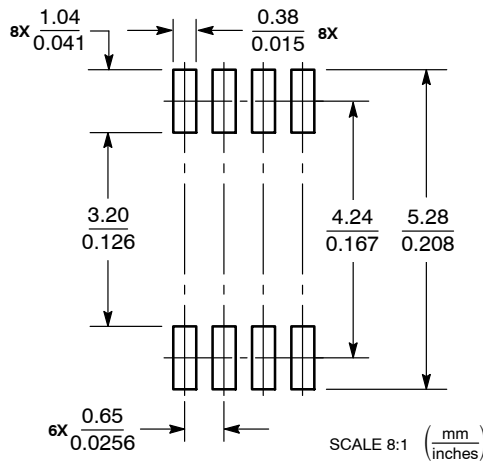


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | -- | -- | 1.10 | -- | -- | 0.043 |
| A1 | 0.05 | 0.08 | 0.15 | 0.002 | 0.003 | 0.006 |
| b | 0.25 | 0.33 | 0.40 | 0.010 | 0.013 | 0.016 |
| c | 0.13 | 0.18 | 0.23 | 0.005 | 0.007 | 0.009 |
| D | 2.90 | 3.00 | 3.10 | 0.114 | 0.118 | 0.122 |
| E | 2.90 | 3.00 | 3.10 | 0.114 | 0.118 | 0.122 |
| e | 0.65 BSC | | | 0.026 BSC | | |
| L | 0.40 | 0.55 | 0.70 | 0.016 | 0.021 | 0.028 |
| HE | 4.75 | 4.90 | 5.05 | 0.187 | 0.193 | 0.199 |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

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Как с нами связаться

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